# MOSFET – Power, Single N-Channel 60 V, 15 mΩ, 39 A

#### **Features**

- Small Footprint (5x6 mm) for Compact Design
- Low R<sub>DS(on)</sub> to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- NVMFS5885NLWF Wettable Flanks Product
- AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			$V_{DSS}$	60	V
Gate-to-Source Voltage	9		$V_{GS}$	±20	V
Continuous Drain Cur-		T <sub>mb</sub> = 25°C	I <sub>D</sub>	39	Α
rent R <sub>ΨJ-mb</sub> (Notes 1, 2, 3)	Steady	T <sub>mb</sub> = 100°C		28	
Power Dissipation	State	T <sub>mb</sub> = 25°C	$P_{D}$	54	W
R <sub>ΨJ-mb</sub> (Notes 1, 2, 3)		T <sub>mb</sub> = 100°C		27	
Continuous Drain Cur-		T <sub>A</sub> = 25°C	I <sub>D</sub>	10.2	Α
rent R <sub>θJA</sub> (Notes 1 & 3)	Steady State	T <sub>A</sub> = 100°C		7.2	
Power Dissipation		T <sub>A</sub> = 25°C	$P_{D}$	3.7	W
R <sub>θJA</sub> (Notes 1 & 3)		T <sub>A</sub> = 100°C		1.8	
Pulsed Drain Current	T <sub>A</sub> = 25	°C, t <sub>p</sub> = 10 μs	I <sub>DM</sub>	179	Α
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>stg</sub>	-55 to 175	°C
Source Current (Body Diode)			I <sub>S</sub>	46	Α
Single Pulse Drain-to-Source Avalanche Energy (T <sub>J</sub> = 25°C, V <sub>DD</sub> = 50 V, V <sub>GS</sub> = 10 V, $I_{L(pk)}$ = 18 A, L = 0.3 mH, $I_{RG}$ = 25 $I_{L(pk)}$			E <sub>AS</sub>	49	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Mounting Board (top) - Steady State (Notes 2, 3)	$R_{\Psi J-mb}$	2.8	°C/W
Junction-to-Ambient - Steady State (Note 3)	$R_{\theta JA}$	41	

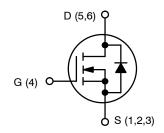
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Psi  $(\Psi)$  is used as required per JESD51-12 for packages in which substantially less than 100% of the heat flows to single case surface.
- 3. Surface-mounted on FR4 board using a 650 mm<sup>2</sup>, 2 oz. Cu pad.



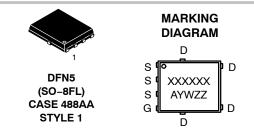
#### ON Semiconductor®

#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX	
60 V	15 mΩ @ 10 V	00.4	
	21 mΩ @ 4.5 V	39 A	



**N-CHANNEL MOSFET** 



A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

#### **ORDERING INFORMATION**

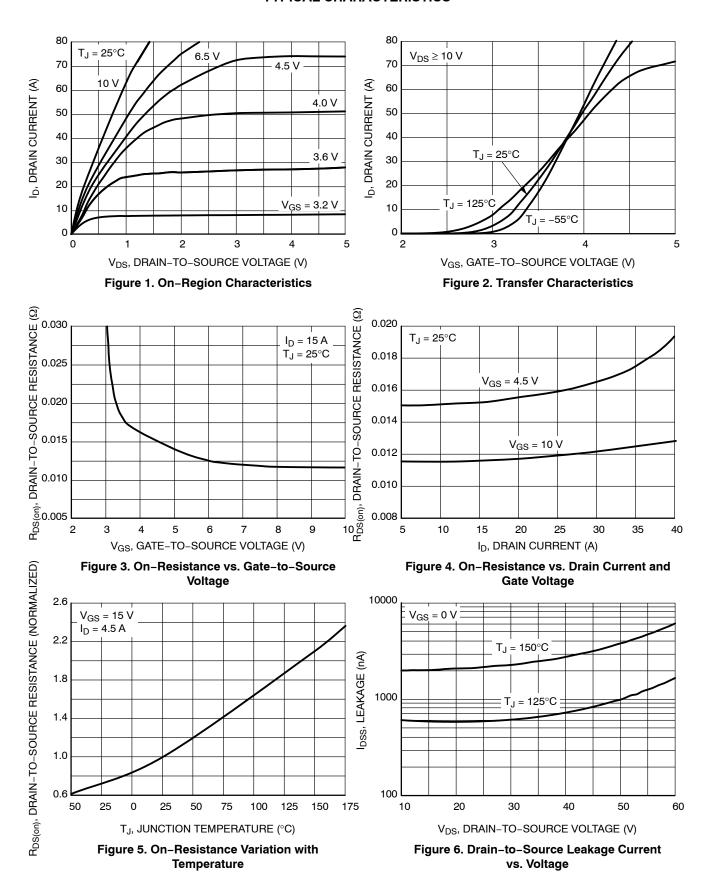
See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS	•	•	L		•	•	
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS}$ = 0 V, $I_D$ = 250 $\mu A$		60			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	Vcs = 0 V	T <sub>J</sub> = 25°C			1.0	μА
		V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 60 V	T <sub>J</sub> = 125°C			10	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{G}$	<sub>S</sub> = ± 20 V			±100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	) = 250 μΑ	1.5		2.5	V
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V,	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		11.6	15	mΩ
		V <sub>GS</sub> = 4.5 V,	I <sub>D</sub> = 15 A		15.2	21	
CHARGES AND CAPACITANCES	-						
Input Capacitance	C <sub>iss</sub>	$V_{GS}$ = 0 V, f = 1 MHz, $V_{DS}$ = 25 V			1340		pF
Output Capacitance	C <sub>oss</sub>				125		
Reverse Transfer Capacitance	C <sub>rss</sub>				85		1
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DS</sub> = 48 V, I <sub>D</sub> = 15 A			12		
Threshold Gate Charge	Q <sub>G(TH)</sub>				1.1		nC
Gate-to-Source Charge	$Q_{GS}$				4.0		
Gate-to-Drain Charge	$Q_{GD}$				6.3		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 10 V, V <sub>DS</sub> =	48 V, I <sub>D</sub> = 15 A		21		nC
SWITCHING CHARACTERISTICS (No	te 5)						
Turn-On Delay Time	t <sub>d(ON)</sub>				10		
Rise Time	t <sub>r</sub>	V <sub>GS</sub> = 4.5 V, V	<sub>'DS</sub> = 48 V,		64		
Turn-Off Delay Time	t <sub>d(OFF)</sub>	$I_D = 15 \text{ A}, R_0$	$G = 2.5 \Omega$		18		ns
Fall Time	t <sub>f</sub>	1			52		
DRAIN-SOURCE DIODE CHARACTER	ISTICS						
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		0.8	1.2	V
		I <sub>S</sub> = 15 A	T <sub>J</sub> = 125°C	125°C 0.7			
Reverse Recovery Time	t <sub>RR</sub>		•		20		
Charge Time	t <sub>a</sub>	V <sub>GS</sub> = 0 V, dls/d	t = 100 A/μs,		15		ns
Discharge Time	t <sub>b</sub>	l <sub>S</sub> = 15 A			5.0		1
Reverse Recovery Charge	Q <sub>RR</sub>				16		nC

Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

#### **TYPICAL CHARACTERISTICS**



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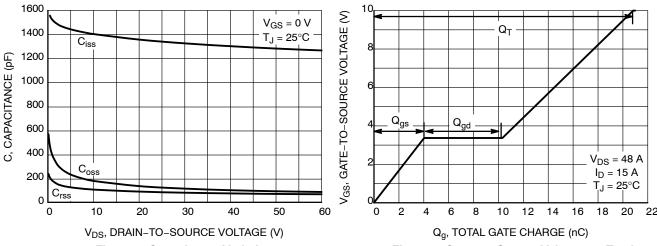


Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Charge

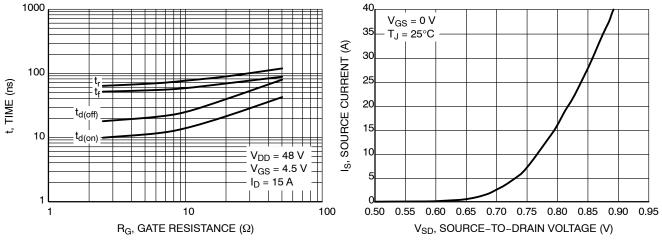


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

Figure 10. Diode Forward Voltage vs. Current

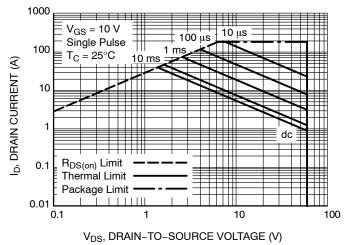


Figure 11. Maximum Rated Forward Biased Safe Operating Area

#### **TYPICAL CHARACTERISTICS**

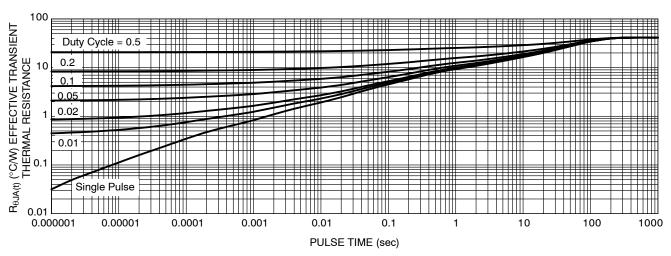


Figure 12. Thermal Response

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
NVMFS5885NLT1G	V5885L	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5885NLWFT1G	5885LW	DFN5 (Pb-Free)	1500 / Tape & Reel
NVMFS5885NLT3G	V5885L	DFN5 (Pb-Free)	5000 / Tape & Reel
NVMFS5885NLWFT3G	5885LW	DFN5 (Pb-Free)	5000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



0.10

0.10

SIDE VIEW

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA ISSUE N

**DATE 25 JUN 2018** 

#### NOTES:

BURRS

- DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETER.
  DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE

	MILLIMETERS			
DIM	MIN	NOM	MAX	
Α	0.90	1.00	1.10	
A1	0.00		0.05	
b	0.33	0.41	0.51	
С	0.23	0.28	0.33	
D	5.00	5.15	5.30	
D1	4.70	4.90	5.10	
D2	3.80	4.00	4.20	
E	6.00	6.15	6.30	
E1	5.70	5.90	6.10	
E2	3.45	3.65	3.85	
е	1.27 BSC			
G	0.51	0.575	0.71	
K	1.20	1.35	1.50	
L	0.51	0.575	0.71	
L1	0.125 REF			
M	3.00	3.40	3.80	
A	0 0		12 °	

#### **GENERIC** MARKING DIAGRAM\*



XXXXXX = Specific Device Code

= Assembly Location Α

Υ = Year W = Work Week ZZ = Lot Traceability

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present. Some products may not follow the Generic Marking.





**DETAIL A** 

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	DFN5 5x6, 1.27P (SO-8FL)		PAGE 1 OF 1	

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